

Amendments to the Claims:

Please cancel claims 45 and 57. Please amend claims 46-56 and 58-65, and please add new claim 73 as follows:

1-45. (Cancelled)

46. (Currently Amended) The planarizing pad of claim 55 45—wherein the texture elements have a plurality of abrasive particles embedded therein.

47. (Currently Amended) The planarizing pad of claim 55 45—wherein the texture elements include partially spherical droplets.

48. (Currently Amended) The planarizing pad of claim 55 45—wherein the texture elements have a cross-sectional dimension of from approximately 50 microns to approximately 200 microns.

49. (Currently Amended) The apparatus of claim 55 45—wherein the texture elements project from the support portion by a distance of from about 10 microns to about 200 microns.

50. (Currently Amended) The planarizing pad of claim 55 45—wherein the support portion is elongated in a longitudinal direction.

51. (Currently Amended) The planarizing pad of claim 55 45—wherein the support portion has a generally circular planform shape.

52. (Currently Amended) The planarizing pad of claim 55 45—wherein the support portion includes a support material, further comprising an adhesive material between the support material and the texture elements.

53. (Currently Amended) The planarizing pad of claim 5545, further comprising a selected chemical agent embedded in the texture elements.

54. (Currently Amended) The planarizing pad of claim 53 wherein the selected chemical agent includes at least one of a surfactant or and an oxidizer.

55. (Currently Amended) ~~The planarizing pad claim 45~~ A planarizing pad for planarizing a microelectronic substrate, comprising:

a generally planar support portion; and

a plurality of texture elements disposed on the support portion, portions of the texture elements being spaced apart from each other and projecting from the support portion, the individual texture elements having a generally smooth upper surface, smoothly transitioning to a generally smooth side surface without asperities, wherein the texture elements have a first spacing in a first region of the support portion and a second spacing in a second region of the support material with the first spacing different than the second spacing.

56. (Currently Amended) The planarizing pad of claim 55 ~~45~~ wherein the texture elements and the support portion have the same chemical composition.

57. (Cancelled)

58. (Currently Amended) The planarizing pad of claim 64 ~~57~~ wherein the texture elements have a plurality of abrasive particles embedded therein.

59. (Currently Amended) The planarizing pad of claim 64 ~~57~~ wherein the texture elements include partially spherical droplets.

60. (Currently Amended) The planarizing pad of claim 64 57 wherein the texture elements have a cross-sectional dimension of from approximately 50 microns to approximately 200 microns.

61. (Currently Amended) The planarizing pad of claim 64 57 wherein the texture elements project from the surface of the support material by a distance of from about 10 microns to about 200 microns.

62. (Currently Amended) The planarizing pad of claim 64 57 wherein the support portion includes a support material, further comprising an adhesive material between the support material and the texture elements.

63. (Currently Amended) The planarizing pad of claim 6457, further comprising a selected chemical agent embedded in the texture elements.

64. (Currently Amended) The planarizing pad of claim 57 A planarizing pad for planarizing a microelectronic substrate, comprising:

a support portion; and

a plurality of discrete texture elements disposed on the support portion, the texture elements being initially separate from the support portion and subsequently bonded to the support portion with portions of the texture elements being spaced apart from each other and projecting from the support portion, the individual texture elements having a generally smooth upper surface, wherein the texture elements have a first spacing in a first region of the support portion and a second spacing in a second region of the support portion with the first spacing different than the second spacing.

65. (Currently Amended) The planarizing pad of claim 64 57 wherein the texture elements and the support portion have the same chemical composition.

66-72. (Cancelled)

73. (New) A planarizing pad for planarizing a microelectronic substrate, comprising:

a generally planar support portion having a surface; and

a plurality of texture elements disposed on the surface of the support portion, portions of the individual texture elements being spaced apart from each other and projecting from the support portion, the individual texture elements having a generally smooth upper surface, smoothly transitioning to a generally smooth side surface without asperities, wherein the texture elements cover less than 20 percent of the surface of the support portion, and wherein the individual texture elements have a cross-sectional dimension of from approximately 50 microns to 100 microns.